

APPLICABLE STANDARD					
Rating	Operating Temperature Range	-55 °C to 85 °C ⁽¹⁾	Storage Temperature Range	-40 °C to 60 °C ⁽²⁾	
	Voltage	50 V AC/DC	Storage Humidity Range	Relative humidity 85% max (Not dewed)	
	Current	0.4 A	Operating Humidity Range		
SPECIFICATIONS					
ITEM		TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION					
General Examination		Visually and by measuring instrument.	According to drawing.	x	x
Marking		Confirmed visually.		x	x
ELECTRIC CHARACTERISTICS					
Contact Resistance		100 mA(DC or 1000Hz)	60mΩ MAX.	x	—
Insulation Resistance		100 V DC.	50 MΩ MIN.	x	—
Voltage Proof		200 V AC for 1 min.	No flashover or breakdown.	x	—
MECHANICAL CHARACTERISTICS					
Insertion and Withdrawal Forces		Measured by applicable connector.	Insertion Force: 36 N MAX. Withdrawal Force: 4.8 N MIN.	x	—
Mechanical Operation		10 times insertions and extractions.	① Contact Resistance : 80mΩ MAX. ② No damage, crack and looseness of parts.	x	—
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.	① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.	x	—
Shock		490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.		x	—
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ~ 95 %, 96±4 h.	① Contact Resistance : 80mΩ MAX. ② Insulation Resistance : 50 MΩ MIN.	x	—
Rapid Change of Temperature		Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2~3 MIN)	③ No damage, crack and looseness of parts.	x	—
Cold		Exposed at -55°C, 96±4 h	① Contact Resistance : 80mΩ MAX.	x	—
Dry Heat		Exposed at 85°C, 96±4 h	② No damage, crack and looseness of parts.	x	—
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25±5 PPM for 96±4 h. (Test standard: IEC 68)	Contact Resistance : 80mΩ MAX.	x	—
Resistance to Soldering Heat		1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 2) Soldering irons : 360°C MAX. for 5 sec.	No deformation of case of excessive looseness of the terminal.	x	—
Solderability		Soldered at solder temperature 240±3°C for immersion duration, 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△					
REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB.			APPROVED	HT. YAMAGUCHI	20200406
			CHECKED	HT. YAMAGUCHI	20200406
			DESIGNED	YY. YOSHIHARA	20200403
			DRAWN	YY. YOSHIHARA	20200403
Unless otherwise specified, refer to IEC 60512.					
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-369481-00-00
HRS	SPECIFICATION SHEET		PART NO.	FX25-80P-0. 4SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL575-4002-0-005	△ 2/1

